

IN THE SPECIFICATION

Please replace the paragraph at page 15, line 24, to page 16, line 8 with the following rewritten paragraph:

20 parts of a bisphenol A-type epoxy resin "Epikote 828" (epoxy equivalent 190, manufactured by Japan Epoxy Resins Co., Ltd.) and 35 parts of a cresol novolak-type epoxy resin "Epiclon N-673" (epoxy equivalent 215, softening point 78°C, manufactured by Dainippon Ink and Chemicals, Inc.) were heat-dissolved in 2-butanone while being stirred, and the solution was then cooled to room temperature. Subsequently, 45 parts of a 2-butanone solution of a triazine structure-containing phenolic novolak resin, "Phenolite LA-7052" (nonvolatile content 60%, nonvolatile content phenolic hydroxyl group equivalent 120, manufactured by Dainippon Ink and Chemicals, Inc.), 70 parts of a cyclohexanone solution of a phenoxy resin "YL-6746H30" (nonvolatile content 30% by weight, weight average molecular weight 30,000, manufactured by Japan Epoxy Resins Co., Ltd.) comprising a bixylenol-type epoxy resin "Epikote YX-4000" (epoxy equivalent 185, manufactured by Japan Epoxy Resins Co., Ltd.) and bisphenol S, further 18 parts of spherical silica and 2 parts of pulverized ~~pulverizing~~ silica were added to prepare a resin varnish of a thermosetting resin composition. This varnish type of the thermosetting resin composition was coated on a release-treated surface of a polyethylene naphthalate film having a thickness of 38 μm , and dried at from 80 to 120°C (on average 100°C) (residual amount of the solvent 2% by weight) to form a thermosetting resin composition layer having a film thickness of 10 μm . This layer was wound up in the form of a roll.